

II. Company Introduction

I. Date Established: May 15, 1997

II. Company History

- 1997** May -- Powertech Technology Inc. established, with paid-in Capital of NT\$ 600 million.
- Aug -- Received Powerchip's DRAM and Macronix's FLASH testing order and started memory IC testing services.
- 1998** Feb -- Received Securities and Futures Commission, Ministry of Finance approval for public offering.
- March -- Started construction for PTI's Hsinpu Plant.
- May -- Cash Injection of NT\$ 600 million, Paid-in Capital of NT\$ 1.2 billion.
- May -- Passed ISO 9002 Quality Management System Certification (Testing).
- 1999** Jan -- Mr. Duh Kung Tsai from the Kingston Group joined as Chairman.
- May -- Cash injection of NT\$ 800 million, Paid-in Capital of NT\$ 2.0 billion.
- June -- Stage One of PTI Hsinpu Plant completed, rented to Powerchip's Chubei Branch.
- Aug -- Construction started on Stage two of PTI Hsinpu Plant.
- Received testing order from Toshiba for DRAM and SST for Flash.
- 2000** April -- Report prepared for the Taiwan Stock Exchange and GreTai Securities Market, started to receive guidance for listing on TSE and OTC.
- June -- PTI Hsinpu Plant completed and relocated to new plant.
- Oct -- Purchase backend equipment from Powerchip's Chubei Branch and added packaging business. Then obtained Powerchip's DRAM packaging orders and started to provide customers turnkey packaging and testing services.
- 2001** Jan -- Become listed as bonded factory.
- April -- Received quality certification from Mitsubishi.
- May -- Received ISO 9002: 1994 Quality Management System Certification (Packaging, Testing).
- Aug -- Surplus and Capital Reserve Capital Increase of NT\$ 218 million, Paid-in Capital of NT\$ 2.218 billion.
- 2002** Jan -- Received quality certification from Hitachi.
- March -- Received quality certification of testing and packaging from TOSHIBA.
- Received TOSHIBA FLASH packaging and testing orders, provide turnkey services for TOSHIBA packaging and testing.
- June -- Passed quality certification from Sun Microsystems.
- Sept -- Cash Injection of NT\$ 119 million, Surplus Capital Increase of NT\$ 134.229 million, Paid-in Capital of NT\$ 2.463129 billion.
- Purchased Hukuo Plant's Land and Plant of FICTA.
- Oct -- Company Shares listed for trading as Emerging Stock of Gretai Securities

- Market.
- Nov -- Received quality certification from M-Systems and Sankyo.
- 2003** Jan -- Received ISO 14001:1996 Environmental Management Systems Certification.
- March -- Received quality certification from Sony.
- April -- Company Shares listed for trading on Gretai Securities Market.
 -- Company headquarters moved to Hukuo Plant in Hsinchu Industrial Park .
 -- Received quality certification from ProMos.
- May -- Received quality certification from IBM.
- July -- Received quality certification from Hynix and received Hynix orders.
 -- Formally received ProMos orders.
- Aug -- Received ISO 9002: 2000 Quality Management System Certification
- Sept -- Surplus Capital Increase of NT\$ 149.371 million, Paid-in Capital of NT\$ 2.6125 billion.
- Dec -- Received quality certification from Xanavi.
- 2004** Jan -- WBGA packaging formally into volume production.
- April -- Received land from the Hukuo Industrial Park about 3000 pings, for expansion of future operations.
 -- Received quality certification from Renesas.
- July -- DDR2 formally into volume production.
- Sept -- Cash Injection of NT\$ 300 million, Surplus Capital Increase of NT\$ 467.5 million, Paid-in Capital of NT\$ 3.38 billion.
 -- Received OHSAS 18001 : 1999 Occupational Health and Safety Management certification.
 -- Started construction on Plant 3.
- Oct -- Received quality certification from Elpida.
- Nov -- Company Shares listed for trading on the Taiwan Stock Exchange.
 -- Foundry grade testing formally into mass production.
- 2005** Feb -- Implemented Green Product (GP) Management System.
- March -- Received quality certification from IBM (uBGA).
 -- Received quality certification from Sharp.
- May -- Received quality certification from Sony Green Partner.
- Sept -- Surplus Capital Increase of NT\$ 625 million, Paid-in Capital of NT\$ 4.005 billion.
 -- Tera Probe, Inc., a joint venture formed in Japan with Elpida, Advantest and Kingston Technology Japan.
- Dec -- Use the “Purchase Method” for simplified merger of 100% owned company, Lijia Investment Ltd.
 -- MCP packaging process into volume production.
 -- Started production of MicroSD Card.
 -- Received ISO 14001 : 2004 Environmental Management System Certification.

- 2006** Jan -- R&D Technology Center Established.
 -- Headquarters (Plant 3) completed for use.
 -- First time issuance of Global Depository Receipts (old shares), listed for trading on the Bourse de Luxembourg.
- Aug -- Surplus Capital Increase of NT\$ 750 million, Paid-in Capital of NT\$ 4.711 billion.
 -- Received ISO/TS 16949: 2002 Certification.
- Nov -- Received land from the Hukuo Industrial Park about 1089 pings, for expansion of future operations.
- Dec -- Received the “2006 Industrial Innovation Outcome Commendation” from the Ministry of Economic Affairs Department of Industrial Technology (MOEA DOIT).
- 2007** Feb -- Started construction of Hukuo Plant 2B
- March -- Issued for the first time the private placement domestic unsecured convertible bonds, with amount issued of NT\$ 3.412 billion.
- July -- Successful developed the wBGA DDP technology, providing the best DRAM stacking solution.
- Aug -- Surplus Capital Increase of NT\$ 853 million, Paid-in Capital of NT\$ 5.563 billion.
 -- Monthly Revenue exceed NT\$ 2 billion formally, packaged volume exceeding 100 million chips.
 -- Received the “2006 Golden Commerce Award” from the MOEA Bureau of Foreign Trade (BFT) for Being Tenth in Actual Import/Export.
- Nov -- Received the “Eight Industrial Elite Award” from the MOEA BFT.
- 2008** Jan -- Hukuo Plant 2B completed for operation.
- March -- Started to provide packaging services for Logic IC.
- June -- Received license from IBM for Metal Post Solder-Chip Connection (MPS-C2) technology. This is a key technology for fine-pitch Flip Chip packaging.
- Aug -- Surplus Capital Increase of NT\$ 7.45 million, Paid-in Capital of NT\$ 6.694 billion.
 -- Formed joint venture, TeraPower Technology Inc, with Japanese company Tera Probe, Inc, with paid-in capital of NT\$ 750 million, and our company holding 49% of the JV.
- Sept -- Received the “2007 Golden Commerce Award” from the MOEA Bureau of Foreign Trade (BFT) for Being Ninth in Actual Import/Export.
- Nov -- Received land from the Hukuo Industrial Park about 5,953 pings, for expansion of future operations.
- 2009** July -- Surplus Capital Increase of NT\$ 386 million, Paid-in Capital of NT\$ 6.694 billion.
- Aug -- Received the “2008 Golden Commerce Award” from the MOEA Bureau of Foreign Trade (BFT) for Being Fifth in Actual Import/Export.
 -- Formed overseas subsidiary Powertech Holding(B.V.I.) Inc.

- Sept -- Acquired Spansion Holdings (Singapore) Pte. Ltd. (name changed to PTI Technology (Singapore) Pte. Ltd.) through Powertech Holding(B.V.I.) Inc., and indirectly obtaining Spansion's MCP packaging and testing plant in Suzhou, China. The China plant was renamed Powertech Technology (Suzhou) Ltd., and the Company formally entered China as a packaging and testing company.
- 2010** March -- Formed subsidiary in the Hsinchu Science Park, Macrotech Technology Inc.
 -- Established US subsidiary Powertech Technology (USA), Inc through overseas subsidiary Powertech Holding (B.V.I.) Inc. to serve as overseas sales and service center.
- April -- Paid-in capital increased to NT\$ 7,042,366,680 after conversion into common shares by convertible bonds .
- Sept -- Paid-in capital increased to NT\$ 7,153,668,040 after conversion into common shares by convertible bonds .
 -- Received the "2009 Golden Commerce Award" from the MOEA Bureau of Foreign Trade (BFT) for Being Fifth in Actual Import/Export.
 -- Received the "Outstanding Innovation Company Award" portion of the 18th Industry Technology Development Award from the MOEA DOIT.
- Dec -- Paid-in capital increased to NT\$ 7,264,969,400 after conversion into common shares by convertible bonds.
- 2011** May -- New Plant in Hukuo started construction.
- Aug -- Surplus Capital Increase of NT\$ 7,264,969,400. Paid-in Capital of NT\$ 7,991,466,340.
 -- Received the "Creating Employment Contribution Award" from the Executive Yuan.
- Sept -- Received the "2010 Golden Commerce Award" from the MOEA Bureau of Foreign Trade (BFT) for Being Sixth in Actual Import/Export.
- Dec -- Established Remuneration Committee.
- 2012** Feb -- Acquired 44% of Greatek Electronics through public tender offer.
- Apr -- During re-election at the extraordinary shareholders' meeting, PTI formally become part of the Greatek Electronics' management.
 -- Institutional director Shiren Investment Company sold more than 50% of company shares owned when it was elected director, so naturally dismissed as company director.
- Aug -- Purchased of company's treasury stocks for the first time, with a capital reduction of NT\$ 200 million, Paid in Capital reduced to NT\$ 7,791,466,340.
- Dec -- For effective use of company resources and tax considerations, liquidated US subsidiary Powertech Technology USA Inc.
- 2013** Jul -- Elpdia Memory Inc. acquired by Micron Technology Inc. and changed the trading entity to Micron Japan.

- Sep -- Received 2012 Golden Trade Award for 10th place.
- Nov -- Grand Opening for plant 3C, and relocated HQ to the new plant.
- 2014** Feb -- Legal settlement reached with Tessera Inc. to early terminate product license agreement which help reducing future services costs.
- Jul -- Acquired 100% shares of Nepes Pte. Ltd. Singapore and changed name to Powertech Technology (Singapore) Pte. Ltd.
- Dec -- Signed investment agreements with Micron Inc. for providing package services in Xian, China.
- Merged Macrotech Technology Inc. and established Hsinchu Science Park branch on the site.
- 2015** Apr -- Became a member of Electronic Industry Citizenship Coalition (EICC).
- May -- Established Powertech Semiconductor (Xian) Co., Ltd.
- Oct -- Signed strategic alliance agreement with Tsinghua Unigroup through private placement.
- 2016** Apr -- Received 2015 Golden Trade Award for 4th place.
- Nov -- Received 2016 Taiwan Top 50 Corporate Sustainability Report Golden Award in Electronic Information Category.
- Certified for ISO 27001 Data Security Management System.
- Dec -- Certified for SA8000 Social Responsibility Management System.
- 2017** Jan -- Established Powertech Technology Japan Ltd.
- Mutual agreement among Powertech Technology Inc. and Tsianghua Unigroup Co., Ltd., and Tibet TouZhanChaungXin Investment Co., Ltd. authorized to terminate share subscription agreement.
- Became a member of Taiwan Alliance for Sustainable Supply and participate in Taiwan packaging and testing industry eco-cloud development program.
- Apr -- Contracted with Micron Inc to acquire its 39.6% holding of Tera Probe, Inc. shares by public tender offer and 100% Micron Akita Inc. operations.
- Jun -- Tera Probe, Inc. became a PTI subsidiary after completed acquisition of Tera Probe, Inc. with 59.44% consolidated holding.
- Aug -- Completed the acquisition of 100% Micron Akita Inc. and name changed to Powertech Technology Akita Inc.
- Nov -- Received 2017 Taiwan Top 50 Corporate Sustainability Report Golden Award in Electronic Information Category.
- 2018** Jan -- Named Top 100 Global Technology Leader by Thomson Reuters.
- Sep -- Groundbreaking for Hsin Chu Science Park Plant III as the Fan-Out Panel-Level Packaging (FOPLP) facility.
- Nov -- Board of Directors appointed Mr. DK Tsai as Chief Strategy Officer and Mr. JY Hung as Chief Executive Officer.
- Received 11th Annual Taiwan Institute for Sustainable Energy Top 50 Corporate Sustainability Report Platinum and Top 50 Corporate Sustainability.